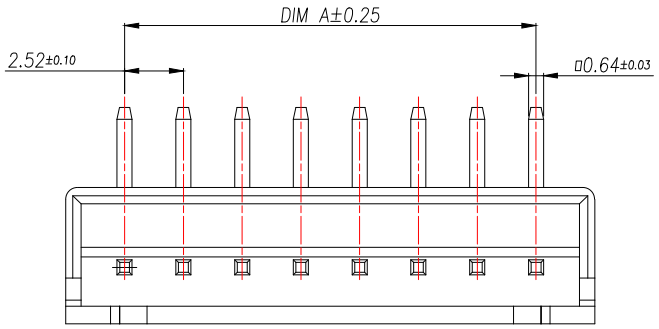
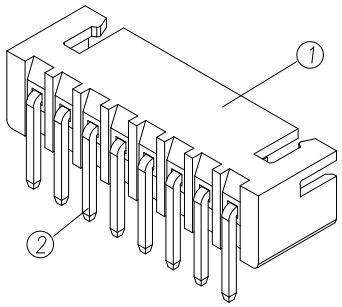
REV.	DESCRIPTION	ECN NO.	NAME	DATE

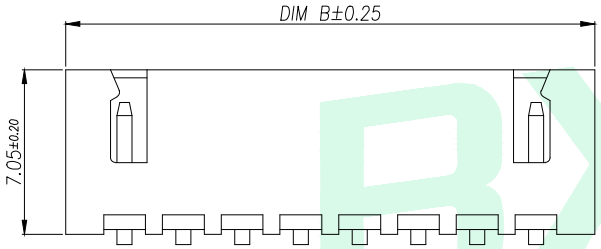


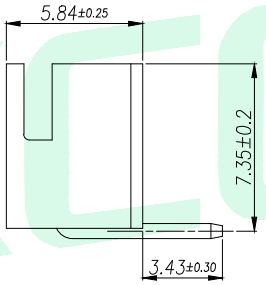


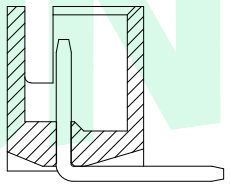
技术要求:

1、塑件材料:PA66 (UL-94V-0)
2、接触件:黄铜镀锡
3、接触电阻:≤10mΩ
4、绝缘电阻:≥1000MΩ
5、额定电压:250V AC DC
6、额定电流:3.0A AC DC
7、耐压:能承受1000V AC/Min ute
8、工作温度:-25°~~+85°
9、可焊性试验:浸锡面积≥95%温度235^{+5}_{-0}°,时间 2.5±0.5秒
10、铅和镉等六大有害物质含量要符合环保要求

PRELIMINARY
DESIGN IS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE

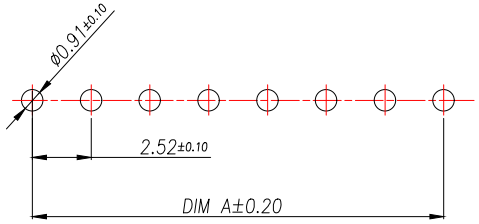






SECTION A-A

Part No	PIN	A	B
WF-XH2.54-2PWZ	2	2.5	7.5
WF-XH2.54-3PWZ	3	5.0	10.0
WF-XH2.54-4PWZ	4	7.5	12.5
WF-XH2.54-5PWZ	5	10.0	15.0
WF-XH2.54-6PWZ	6	12.5	17.5
WF-XH2.54-7PWZ	7	15.0	20.0
WF-XH2.54-8PWZ	8	17.5	22.5
WF-XH2.54-8PWZ	9	20.0	25.0
WF-XH2.54-9PWZ	10	22.5	27.5
WF-XH2.54-11PWZ	11	25.0	30.0
WF-XH2.54-12PWZ	12	27.5	32.5
WF-XH2.54-13PWZ	13	30.0	35.0
.....	...	...	...
WF-XH2.54-20PWZ	20	(20-1)*2.5	(20+1)*2.5



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

序号	名 称	材 料	数 量	附 注
2	Contact	Brass	n*1	电镀(镍):整个表面镀底镍30u"MIN,再镀镍80u".MIN.
1	Wafer	PA66(UL94V-0)	1	本色

GENERAL TOLERANCE

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: WAFER 2.54mm H7.0mm 90° DIP

DWG. NO.: WF-XH2.54-XPWZ

DRAWN: MAX

PART NO.: WF-XH2.54-XPWZ

CHECKED: ELLA

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:
mm	none	1of 1	A4	bxconn

APPROVED: WILL